

PROLABS – XDACBL3M-C

SFP+ Direct Attach Copper Cable Assembly

XDACBL3M-C Overview

PROLABS's XDACBL3M-C SFP+ Direct Attach Copper Cable Assembly are based on 10G Ethernet IEEE 802.3ae standard, Fiber Channel and SFF 8431 standard, and the passive SFP+ Cable is a low cost alternative for short reach applications. The passive design has no signal amplification in the cable assembly. Electronic Dispersion Compensation (EDC) is typically used on the host board designs when passive copper cable assemblies are utilized.

Features

- Up to 11 GBd bi-directional data links
- Compliant with 10GFC
- Compliant with SFF8431
- Hot-pluggable SFP+ footprint
- AC coupled inputs and outputs
- 100 Ohm differential impedance
- Enhanced EMI design
- Single power supply 3.3V
- RoHS Compliance
- Operating temperature range: 0°C to 70°C

Applications

- 10GBASE Ethernet
- 10GFC
- Serial Data Transmission

Ordering Information

Part Number	Description
XDACBL3M-C	SFP+ Direct Attach Copper Cable Assembly, 3 m

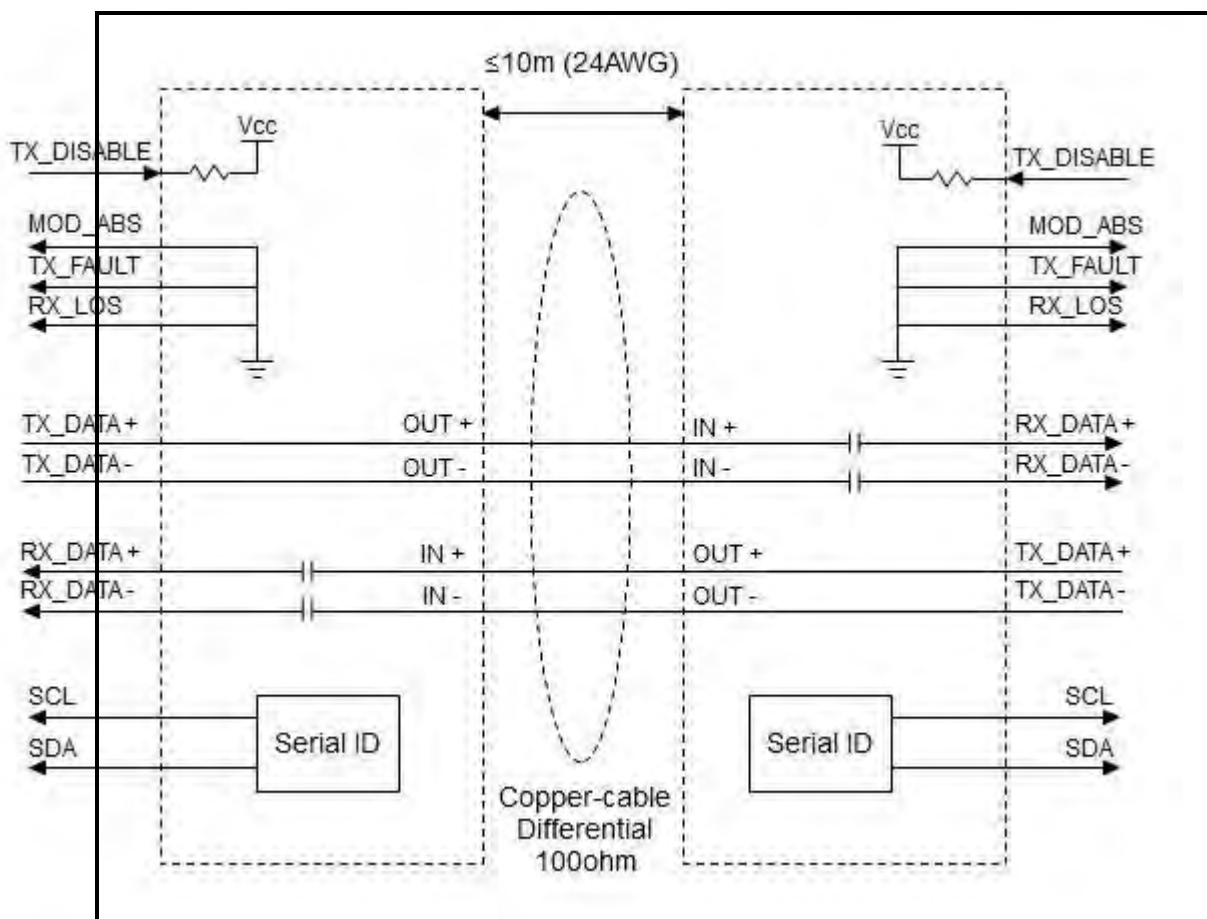
General Specifications

Parameter	Symbol	Min	Typ	Max	Unit	Remarks
Data Rate	DR		10.3125		GBd	IEEE 802.3ae
Bit Error Rate	BER			10^{-12}		
Operating Temperature	T _{OP}	0		70	°C	Case temperature
Storage Temperature	T _{STO}	- 40		85	°C	Ambient temperature
Supply Current	I _S			4	mA	For electrical power interface
Input Voltage	V _{CC}	3	3.3	3.6	V	
Maximum Voltage	V _{MAX}	- 0.5		4	V	For electrical power interface

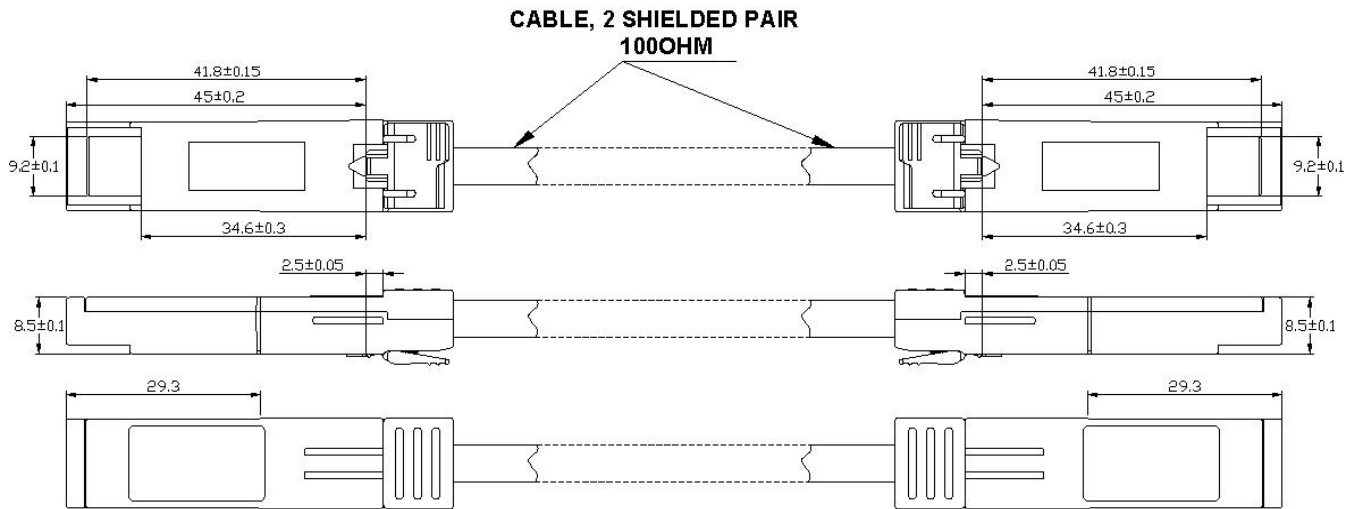
Cable Mechanical Specifications

Parameter	Symbol	Min	Typ	Max	Unit	Remarks
Cable Diameter(24AWG)	D_{IA}		0.255		Inches	
Time Delay Skew(Within Pair)	T_{DS}			100	Ps/10m	
Cable Time Delay	T_d		4.3		ns/m	
Cable Insertion Loss	L_o		10		dB/10m	
Cable Impedance	Z_c	95	100	105	Ohm	

Block Diagram of Transceiver

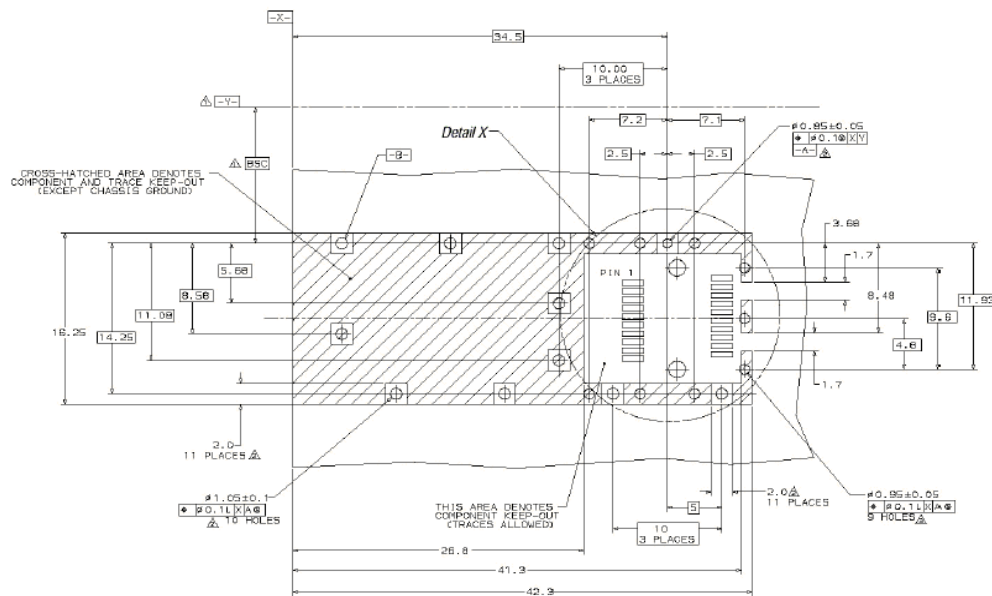



Dimensions




**ALL DIMENSIONS ARE ± 0.2 mm UNLESS OTHERWISE SPECIFIED
UNIT: mm**

PCB Layout Recommendation

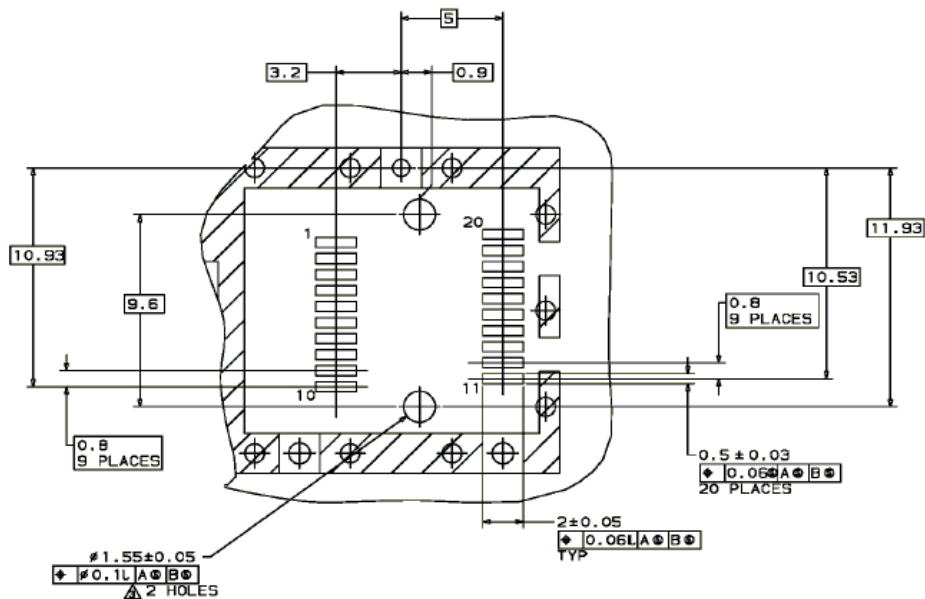
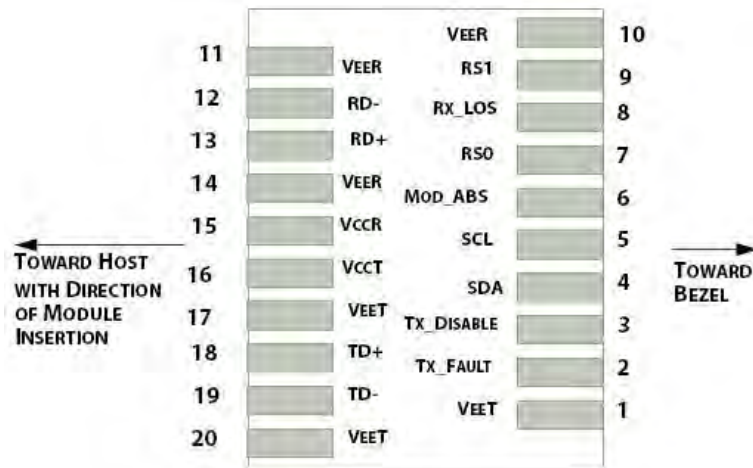


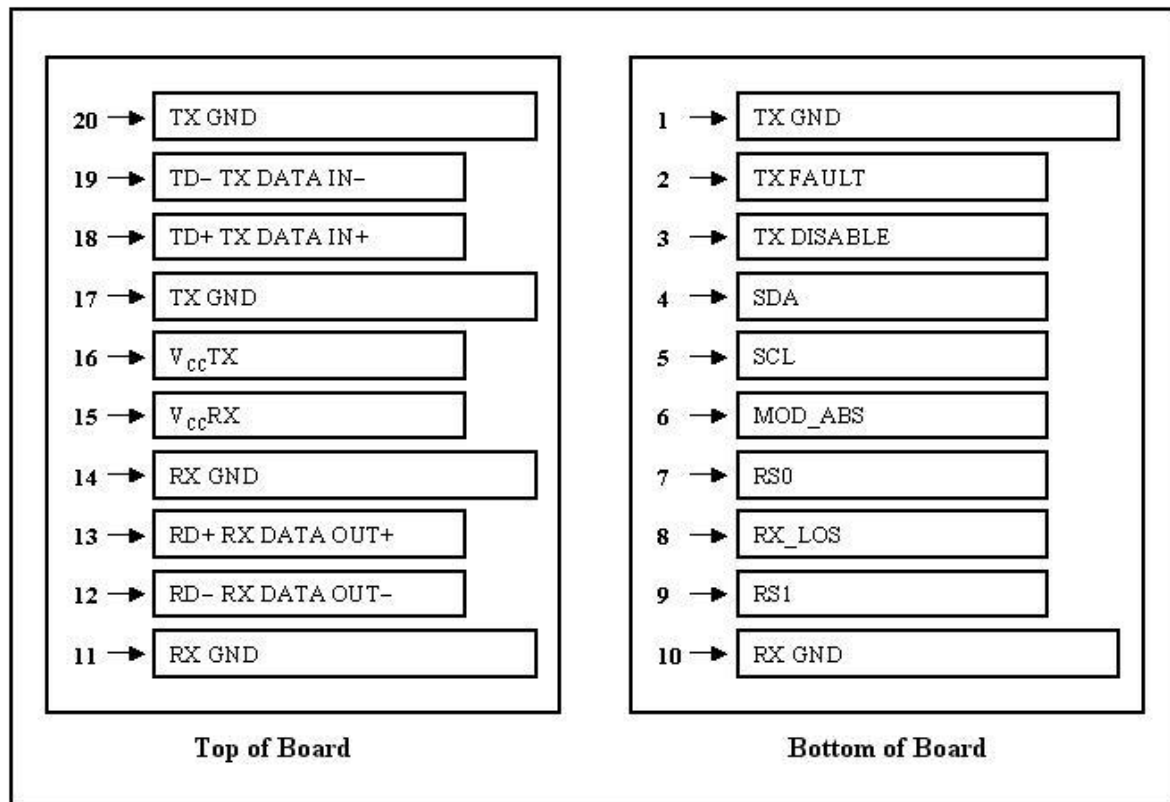
 Datum and Basic Dimension Established by Customer

 Pads and Vias are Chassis Ground, 11 Places

 Through Holes are Unplated

Electrical Pad Layout





Pin Assignment

<i>PIN #</i>	<i>Symbol</i>	<i>Description</i>	<i>Remarks</i>
1	V _{EET}	Transmitter ground (common with receiver ground)	
2	T _{FAULT}	Transmitter Fault.	
3	T _{DIS}	Transmitter Disable. Laser output disable on high or open	
4	SDA	Data line for serial ID	
5	SCL	Clock line for serial ID	
6	MOD_ABS	Module Absent. Grounded within the module	
7	RS0	No connection required	
8	LOS	Loss of Signal indication. Logic 0 indicates normal operation	
9	RS1	No connection required	
10	V _{EER}	Receiver ground (common with transmitter ground)	
11	V _{EER}	Receiver ground (common with transmitter ground)	
12	RD-	Receiver Inverted DATA out. AC coupled	
13	RD+	Receiver Non-inverted DATA out. AC coupled	
14	V _{EER}	Receiver ground (common with transmitter ground)	
15	V _{CCR}	Receiver power supply	
16	V _{CCT}	Transmitter power supply	
17	V _{EET}	Transmitter ground (common with receiver ground)	
18	TD+	Transmitter Non-Inverted DATA in. AC coupled	
19	TD-	Transmitter Inverted DATA in. AC coupled	
20	V _{EET}	Transmitter ground (common with receiver ground)	

References

1. IEEE standard 802.3ae. IEEE Standard Department, 2005.
2. Enhanced 8.5 and 10 Gigabit Small Form Factor Pluggable Module "SFP+" – SFF-8431